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PATENT

Docket No. JCLA7208 :

Date: <u>7</u>- }-

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Page 1

Transmitted herewith for filing is the patent application of

Inventor(s): CHIA-PIN LIN

CHIH-PENG FAN

CHANG-YUN HUNG

SHENG-CHOU LEE

METHOD OF LAMINATING COPPER FOIL ONTO A PRINTED CIRCUIT BOARD

Enclosed are:

- (X) Specification in (11) pages.
- (3) sheets of drawings.
- Return prepaid postcard.

Note:

THIS APPLICATION IS FILED UNSIGNED AND UNPAID

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Docket No.	: JCLA7208
Applicant(s)	: Chia-Pin Lin, Chih-Peng Fan, Chang-Yun Hung, Sheng-Chou Lee
For	

: METHOD OF LAMINATING COPPER FOIL
ONTO A PRINTED CIRCUIT BOARD

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Date of Deposit : July 3, 2001

I hereby certify that the accompanying

Transmittal in Duplicate; Specification 11 pages, 3 sheets of drawings; SIGNED Declaration and Power of Attorney 0 pages; Recordation Form Cover Sheet and Assignment 0 pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Michelle Chang